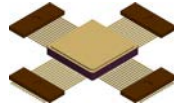


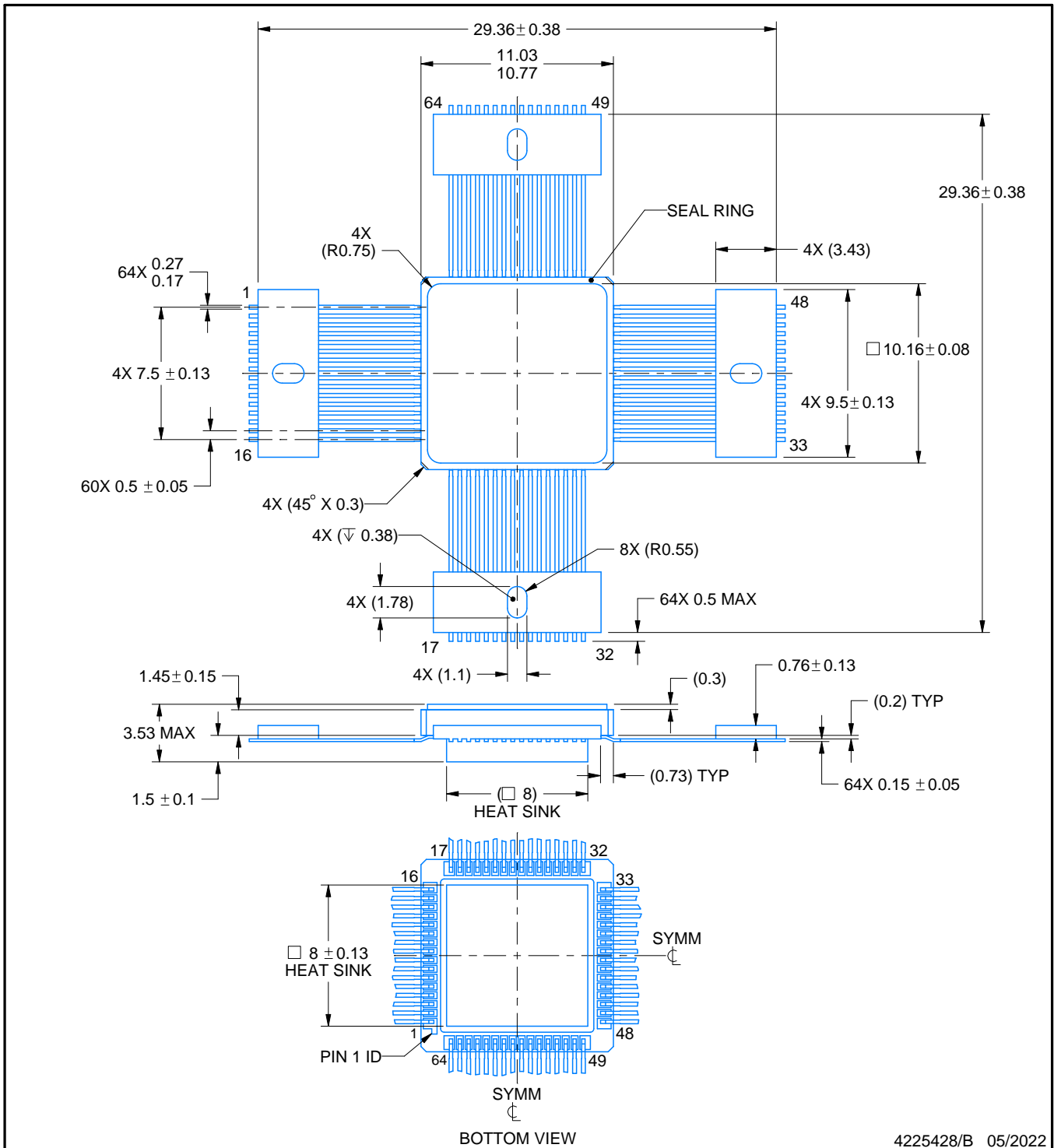
HBE0064B



PACKAGE OUTLINE

CFP - 3.53 mm max height

CERAMIC FLATPACK



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NOTES:

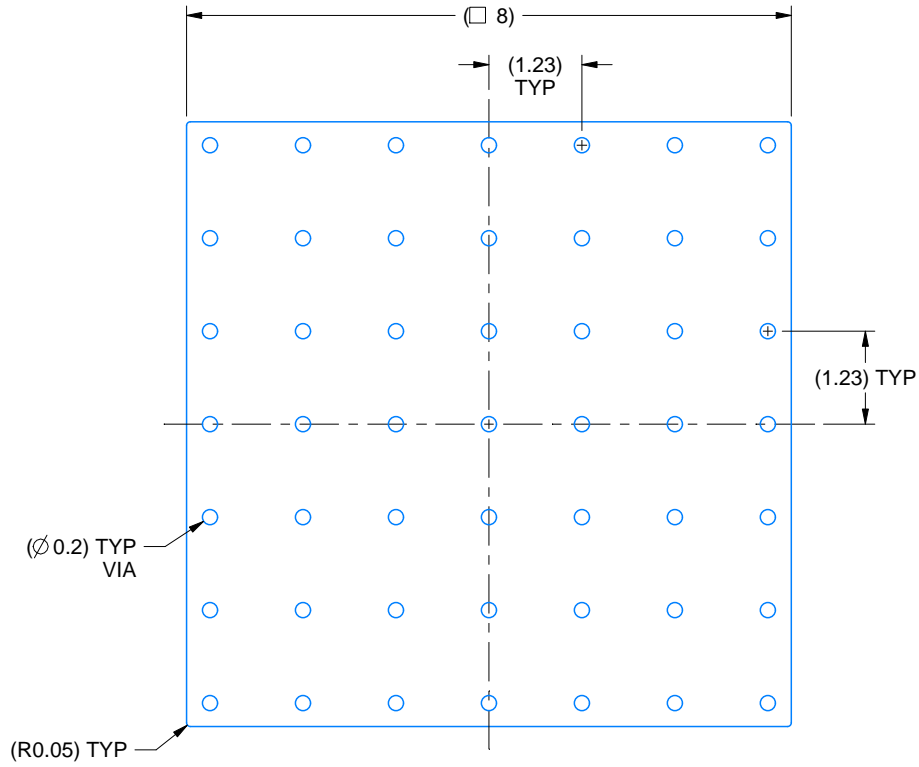
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. Ground pad to be electronic connected to heat sink and seal ring.
5. The leads are gold plated and can be solder dipped.

EXAMPLE BOARD LAYOUT

HBE0064B

CFP - 3.53 mm max height

CERAMIC FLATPACK



HEATSINK LAND PATTERN EXAMPLE
SCALE: 10X

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